



Material Content Data Sheet



Sales Product Name		IPB107N20NA		Issued		29. August 2013			
MA#		MA000898802							
Package		PG-TO263-3-2		Weight*		1471.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	17.562	1.19	1.19	11932	11932	
leadframe	non noble metal	iron	7439-89-6	0.853	0.06		579		
	inorganic material	phosphorus	7723-14-0	0.256	0.02		174		
	non noble metal	copper	7440-50-8	851.691	57.85	57.93	578658	579411	
wire	non noble metal	aluminium	7429-90-5	11.765	0.80	0.80	7993	7993	
encapsulation	organic material	carbon black	1333-86-4	8.544	0.58		5805		
	plastics	epoxy resin	-	93.988	6.39		63858		
	inorganic material	silicondioxide	60676-86-0	467.093	31.74	38.71	317354	387017	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.66	0.66	6561	6561	
plating	non noble metal	nickel	7440-02-0	0.228	0.02		155		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	155	
solder	noble metal	silver	7440-22-4	0.255	0.02		173		
	non noble metal	tin	7440-31-5	0.204	0.01		139		
	non noble metal	lead	7439-92-1	9.743	0.66	0.69	6619	6931	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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